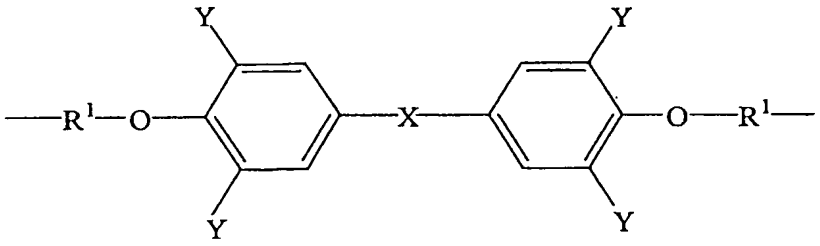
IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A photosensitive resin composition for optical waveguide formation, comprising:

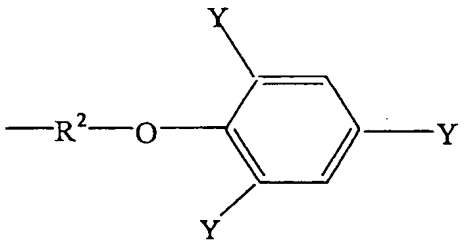
(A) a di(meth)acrylate having the structure represented by the following formula (1):



(1)

wherein R^1 is $-(OCH_2CH_2)_m-$, $-(OCH(CH_3)CH_2)_m-$, or $-OCH_2CH(OH)CH_2-$; X is $-C(CH_3)_2-$, $-CH_2-$,$-O-$, or $-SO_2-$; Y is a hydrogen atom or a halogen atom; m is an integer of 0 to 4;

(B) a mono(meth)acrylate having the structure represented by the following formula (2):



(2)

wherein R^2 is $-(OCH_2CH_2)_p-$, $-(OCH(CH_3)CH_2)_p-$, or $-OCH_2CH(OH)CH_2-$; Y is a hydrogen atom, a halogen atom, Ph-$C(CH_3)_2-$, Ph-, or an alkyl group having 1 to 20 carbon atoms; p is an integer of 0 to 4; Ph is a phenyl group;

(C) a photoradical polymerization initiator; and tris(2-acryloyloxyethyl) isocyanurate, wherein the weight ratio (A/B) of said component (A) to said component (B) is 0.3 to 5.0.

Claim 2 (Canceled).

Claim 3 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein the total amount of said component (A) and said component (B) in said resin composition is 30 wt.% or higher.

Claim 4 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein the amount added of said tris(2-acryloyloxyethyl) isocyanurate is 10 to 25% by weight.

Claim 5 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein the refractive index of the cured product of said resin composition at 25°C and 824 nm is 1.54 or higher.

Claim 6 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein the glass transition temperature (Tg) of the cured product of said resin composition is 80°C or higher.

Claim 7 (Previously Presented): An optical waveguide comprising a core layer, and a clad layer formed by lamination on said core layer, wherein said core layer and/or said clad layer is composed of the cured product of the resin composition of claim 1.

Claim 8 (Previously Presented): A method for manufacturing an optical waveguide, comprising a step of irradiating the resin composition of claim 1 with radiation via a photomask and curing said resin composition.

Claim 9 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein component (A) comprises ethylene oxide-added bisphenol A (meth)acrylic acid ester, ethylene oxide-added tetrabromobisphenol A (meth)acrylic acid ester, bisphenol A epoxy (meth)acrylate obtained by the epoxy ring opening reaction of bisphenol A diglycidyl ether and (meth)acrylic acid, or tetrabromobisphenol A epoxy (meth)acrylate.

Claim 10 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein component (B) comprises phenoxyethyl (meth)acrylate, phenoxyethoxyethyl (meth)acrylate, (meth)acrylate of p-cumyl phenol reacted with ethylene oxide, or 2,4,6-tribromophenoxyethyl (meth)acrylate.

Claim 11 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 3, wherein said total amount is 40 wt.% or higher.

Claim 12 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 3, wherein said total amount is 50 wt.% or higher.

Claim 13 (Currently Amended): The photosensitive resin composition for optical waveguide formation according to claim [[2]] 1, wherein said weight ratio is 0.4 to 4.

Claim 14 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein components (A) and (B) are acrylates.

Claim 15 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein component (C) is present in an amount of 0.01 to 10 wt.%.

Claim 16 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, wherein component (C) is present in an amount of 0.1 to 7 wt.%.

Claim 17 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 5, wherein said refractive index is 1.55 or higher.

Claim 18 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 6, wherein said glass transition temperature is 90°C or higher.

Claim 19 (Previously Presented): The photosensitive resin composition for optical waveguide formation according to claim 1, and having a viscosity of 400-5,000 cp/25°C.